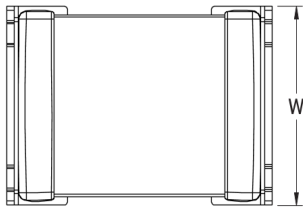
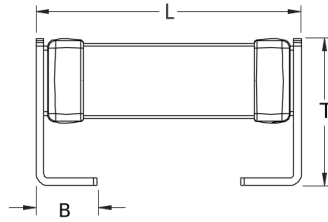


TOP VIEW
Single or Double Chip Stack



PROFILE VIEW
Single Chip Stack



Click [here](#) for the 3D model.

Dimensions

L	3.5mm +/-0.3mm
W	2.6mm +/-0.3mm
T	3.35mm +/-0.10mm
B	0.8mm +/-0.15mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	600

General Information

Series	KPS SMD Comm X7R
Style	Stacked Chip
Description	SMD, MLCC, Stacked, Single Chip, Temperature Stable
Features	Temperature Stable
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	160 mg
Chip Size	1210-1
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	10 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	10% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	50 MOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.